

3.0x2.0mm SURFACE MOUNT LED LAMP

Part Number: KA-3021LVSESK-J3-TR Hyper Red

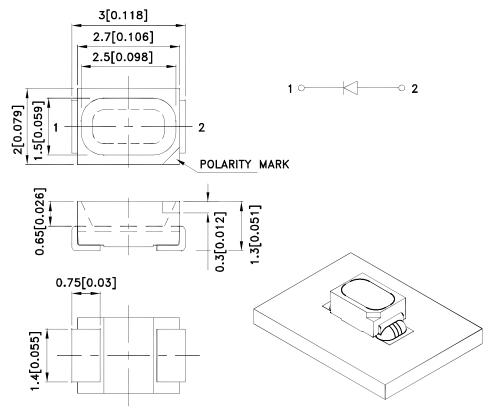
Features

- 3.0mm x 2.0mm, 1.3mm high, only minimum space required.
- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Low current IF=2mA operating.
- RoHS compliant.

Description

The Hyper Red device is based on light emitting diode chip made from AlGaInP.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2 (0.008")$ unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

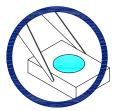
SPEC NO: DSAO8311 **REV NO: V.1A DATE: JUN/01/2016** PAGE: 1 OF 6 ERP: 1201008898 **APPROVED: Wynec CHECKED: Allen Liu** DRAWN: L.T.Zhang

Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

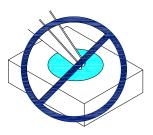
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

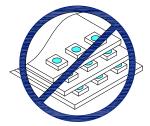


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

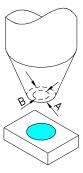




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.



Selection Guide

| Part No. | Emitting Color (Material) | Lens Type | lv (mcd) [2] @ 2mA | | Viewing Angle [1] |
|---------------------|---------------------------|-------------|-----------------------|------|----------------------|
| | | 2. | Min. | Тур. | 201/2 |
| KA 0004LV0F0K I0 TD | Hyper Red (AlGaInP) | Water Clear | 80 | 150 | - 120° |
| KA-3021LVSESK-J3-TR | | | *20 | *45 | |

Notes:

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity / luminous Flux: +/-15%.
 * Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Emitting Color | Тур. | Max. | Units | Test Conditions |
|--------|--------------------------|----------------|------|------|-------|--------------------|
| λpeak | Peak Wavelength | Hyper Red | 640 | | nm | IF=2mA |
| λD [1] | Dominant Wavelength | Hyper Red | 625 | | nm | IF=2mA |
| Δλ1/2 | Spectral Line Half-width | Hyper Red | 20 | | nm | IF=2mA |
| С | Capacitance | Hyper Red | 27 | | pF | VF=0V;f=1MHz |
| VF [2] | Forward Voltage | Hyper Red | 1.8 | 2.1 | V | IF=2mA |
| lr | Reverse Current | Hyper Red | | 10 | uA | V _R =5V |

- Notes: 1. Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to CIE127-2007 standards.
- Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

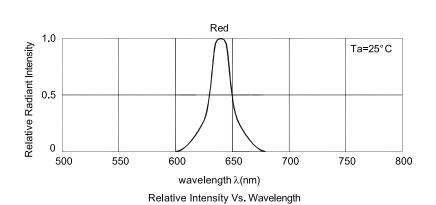
Absolute Maximum Ratings at TA=25°C

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|--------------------------------------|----------------|-------|--|--|--|
| Parameter | Values | Units | | | |
| Power dissipation | 63 | mW | | | |
| DC Forward Current | 30 | mA | | | |
| Peak Forward Current [1] | 150 | mA | | | |
| Reverse Voltage | 5 | V | | | |
| Operating Temperature | -40°C To +85°C | | | | |
| Storage Temperature | -40°C To +85°C | | | | |
| | | | | | |

Notes:

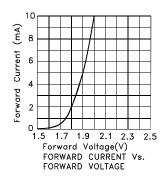
- 1.1/10 Duty Cycle, 0.1ms Pulse Width.
 Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

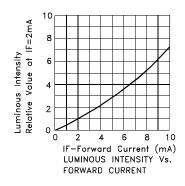
SPEC NO: DSAO8311 **REV NO: V.1A** DATE: JUN/01/2016 PAGE: 3 OF 6 ERP: 1201008898 **APPROVED: Wynec CHECKED: Allen Liu** DRAWN: L.T.Zhang

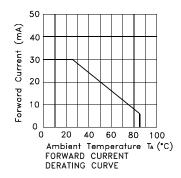


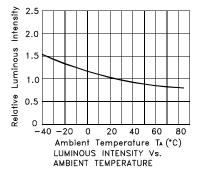
Hyper Red

KA-3021LVSESK-J3-TR



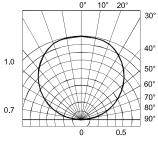






PAGE: 4 OF 6

ERP: 1201008898



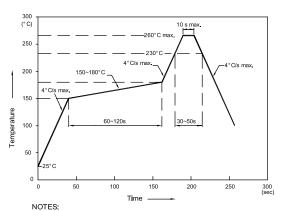
SPATIAL DISTRIBUTION

SPEC NO: DSAO8311 REV NO: V.1A DATE: JUN/01/2016
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KA-3021LVSESK-J3-TR

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



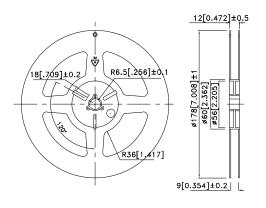
- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature
- to high temperature.
 3.Number of reflow process shall be 2 times or less.

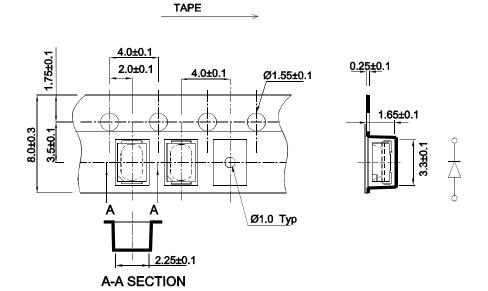
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

1.4

Tape Dimensions (Units : mm)

Reel Dimension

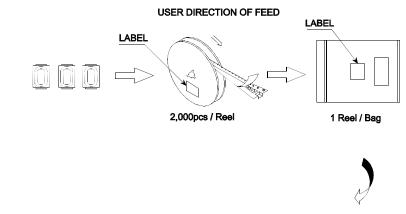


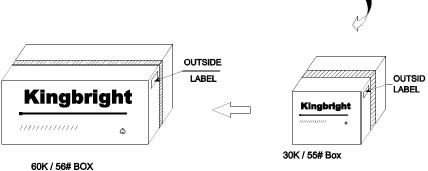


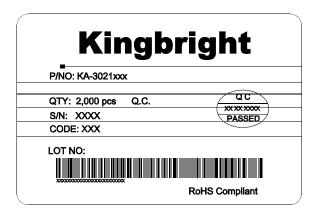
SPEC NO: DSAO8311 APPROVED: Wynec REV NO: V.1A CHECKED: Allen Liu DATE: JUN/01/2016 DRAWN: L.T.Zhang PAGE: 5 OF 6 ERP: 1201008898

PACKING & LABEL SPECIFICATIONS

KA-3021LVSESK-J3-TR







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 SPEC NO: DSAO8311
 REV NO: V.1A
 DATE: JUN/01/2016
 PAGE: 6 OF 6

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